

PRESS RELEASE

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Semilab Licenses Implant and Metal Thickness Metrology Technology from Applied Materials

BUDAPEST, Hungary. September xx, 2008 – Semilab Co. Ltd., a leading supplier of non-contact wafer mapping metrology solutions for the semiconductor and solar cell industries, announced today that it has licensed key patents and transferred relevant know-how from Applied Materials, Inc. The acquired intellectual property (IP) covers technology and systems used in semiconductor applications for measuring implant and metal thickness.

“We are excited to expand our line of advanced metrology solutions for characterizing semiconductor material and processes,” said Tibor Pavelka, CEO of Semilab. “This technology provides critical in-line parametric measurement capability on product wafers, covering implant junction depth and dose monitoring, and metal thickness, via and interconnect resistance measurements.”

Implant metrology systems are immediately available for shipment to Semilab’s customers.

“This agreement is a winning strategy for Semilab, enabling the company to cost-effectively leverage innovative technology to its best advantage.” said Chris Talbot, senior director of Applied’s Strategic Licensing unit.

Terms of the agreement were not disclosed.

About Semilab

Semilab Co. Ltd., headquartered in Budapest, Hungary, was founded in 1989 and pioneered minority carrier lifetime as a tool for metal contamination detection in silicon. Semilab is a leading supplier of non-contact wafer mapping metrology solutions for the global semiconductor and solar cell R&D and manufacturing markets with an installed base of over 700 systems. Current products include the WT2000 bench top and WT3000 FOUP automated mapping tools with modules for the wafer mapping of microPCD lifetime, SPV diffusion

length, VQ gate dielectric properties and JPV implant sheet resistance. Semilab's web site is located at <http://www.Semilab.com>.